



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	7	0.5mm (19.685mil)	NPTH	Round
A	1	0.711mm (28mil)	PTH	Round
◇	1	0.712mm (28.012mil)	PTH	Round
○	10	0.85mm (33.465mil)	PTH	Round
⊙	2	0.914mm (35.984mil)	PTH	Round
▽	4	1.016mm (40mil)	PTH	Round
⊗	4	1.05mm (41.339mil)	PTH	Round
□	2	1.067mm (42mil)	PTH	Round
C	1	1.092mm (42.992mil)	PTH	Round
D	1	1.092mm (43mil)	PTH	Round
E	2	1.1mm (43.307mil)	PTH	Round
◇	4	1.15mm (45.276mil)	PTH	Round
□	4	1.151mm (45.3mil)	PTH	Round
⊗	3	1.27mm (50mil)	PTH	Round
⊙	3	1.3mm (51.181mil)	PTH	Round
⊗	5	1.321mm (52mil)	PTH	Round
○	4	1.5mm (59.055mil)	PTH	Round
⊗	8	1.6mm (63mil)	PTH	Round
F	4	1.7mm (66.929mil)	PTH	Round
⊗	21	2mm (78.74mil)	PTH	Round
B	4	2.083mm (82mil)	PTH	Round
⊗	4	3.5mm (137.795mil)	PTH	Round
99 Total				

Drill Table

**DESIGN INFORMATION**

BOARD SIZE (REFER TO ARRAY/PANEL PROFILING INFORMATION)

Number of Layers : 2  
 MIN. TRACK WIDTH: 8 MIL  
 MIN. CLEARANCE: 8 MIL  
 MIN. VIA PAD SIZE: 16 MIL

MINIMUM ANNULAR RING 0.05mm (2ML) EXTERNAL  
 PER IPC-D-275 CLASS 2 LEVEL C  
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:  
 FR-408  FR-4 High Tg  OTHER \_\_\_\_\_

THICKNESS:  62 MIL (1.6mm) +/-10%  OTHER \_\_\_\_\_

TOLERANCE:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_

BOW & TWIST:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_

COPPER THICKNESS (FINISHED):  
 OUTER:  1.4MIL (1oz)  2MIL (1.4oz)  2.8MIL (2oz)  
 INNER SIGNAL:  1.4MIL (1oz)  2.8MIL (2oz)  N/A

DRILLING:  
 REFERENCE:  AS SHOWN  NC\_DRILL FILES  
 PTH MIN COPPER THICKNESS:  1MIL  OTHER \_\_\_\_\_

BOARD FINISH:  
 SILKSCREEN:  TOP  BOTTOM  
 SILKSCREEN COLOR:  WHITE  OTHER \_\_\_\_\_

SOLDER RESIST COLOR:  
 GREEN  BLUE  OTHER \_\_\_\_\_

SURFACE FINISH:  IMMERSION GOLD (ENIG)  ENEPIG  
 IMM. TIN/SILVER OR EQUIV  OTHER Pb FREE HASL

ARRAY/PANEL:  CUT AND TRIM PER MECH LAYER 1  
 N.C. ROUTE  V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
 ANSI IPC-A-600F CLASS ->  1  2  3  
 UL 94V-0  RoHS  OTHER PER ORDER

ADDITIONAL REQUIREMENTS:  
 MICROSECTION:  YES  
 BARE BOARD ELEC. TEST:  NONE  REQUIRED  PER ORDER  
 MANUFACTURER'S UL:  RAIL  METAL  SILK



PROJECT TITLE:  
UCC28630

DESIGNED FOR:  
Public Release

FILE NAME:  
PMP9643.PcbDoc

ENGINEER:  
Billy Long

LAYOUT BY:  
Brian Gaynor

SCALE: 1.09

ALTIM DESIGNER VERSION:  
10.0.0.27009



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP9643

REV: E2

SVN REV: Not In VersionControl

LAYER NAME = ~~0005~~ Fabrication Drawing

PLOT NAME = Fabrication Drawing

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